



## Material Content Data Sheet



Sales Product Name	BSZ0908ND			Issued		29. August 2013		
MA#	MA000987418							
Package	PG-WISON-8-1			Weight*		23.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.011	0.05		456	
	noble metal	gold	7440-57-5	0.041	0.18		1770	
	inorganic material	silicon	7440-21-3	0.214	0.93	1.16	9258	11484
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		125	
	non noble metal	zinc	7440-66-6	0.012	0.05		499	
	non noble metal	iron	7439-89-6	0.230	1.00		9980	
	non noble metal	copper	7440-50-8	9.354	40.52	41.58	405246	415850
wire	non noble metal	copper	7440-50-8	0.274	1.19	1.19	11877	11877
encapsulation	organic material	carbon black	1333-86-4	0.025	0.11		1084	
	plastics	epoxy resin	-	1.288	5.58		55815	
	inorganic material	silicondioxide	60676-86-0	11.195	48.49	54.18	484993	541892
leadfinish	non noble metal	tin	7440-31-5	0.360	1.56	1.56	15603	15603
plating	noble metal	silver	7440-22-4	0.076	0.33	0.33	3294	3294
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com